

DMSMS NOTICE

DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES

1. TITLE MICROCIRCUIT, DIGITAL, ADVANCED CMOS, RADIATION HARDENED, HEX INVERTER, MONOLITHIC SILICON – FAB MIGRATION		2. DOCUMENT NUMBER SPO-2014-D-0004	
		3. DATE (Year, Month, Date) 2014 February 14	
4. MANUFACTURER NAME AND ADDRESS CAES 4350 CENTENNIAL BOULEVARD COLORADO SPRINGS, COLORADO 80907-3486		5. MANUFACTURER POINT OF CONTACT (NAME) MR. TIM MEADE	
		6. MANUFACTURER POINT OF CONTACT TELEPHONE (719) 594-8048	
		7. MANUFACTURER POINT OF CONTACT EMAIL tim.l.meade@cobhamaes.com	
8. CAGE CODE 65342	9. MANUFACTURER FINAL ORDER DATE SEE COMMENTS BELOW	10. PRODUCT IDENTIFICATION CODE C004A	11. BASE PART UT54ACS04
12. BLANK		13. SMD NUMBER 96516	14. DEVICE TYPE DESIGNATOR 01
		15. RHA LEVELS NON, R, F, G, AND H	16. QML LEVEL Q AND V
		17. NON QML LEVEL N/A	18. BLANK
19. COMMENTS CAES IS ISSUING THIS DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE AND PRODUCT CHANGE NOTIFICATION TO ANNOUNCE THE FOUNDRY MIGRATION OF DEVICE TYPE 01 FROM 1.2UM RADIATION-HARDENED CMOS TO ON-SEMICONDUCTOR'S 0.6UM C5U COMMERCIAL RADIATION-HARDENED CMOS PROCESS. BECAUSE THE MIGRATED DEVICE IS FORM, FIT, AND FUNCTIONAL TO THE LEGACY DEVICE, IT WILL CONTINUE TO SHIP AS DEVICE TYPE 01. AS PART OF THIS PROCESS MIGRATION, THE RADIATION HARDNESS ASSURANCE LEVEL "H" AND CASE OUTLINE "C" WILL NO LONGER BE AVAILABLE FROM AN APPROVED SOURCE OF SUPPLY. CAES WILL ACCEPT ORDERS FOR RHA LEVEL "H" AND PACKAGE OUTLINE "C" ON A "FIRST COME, FIRST SERVED" BASIS, THROUGH JUNE 2014 OR UNTIL INVENTORY EXHAUSTS. ADDITIONALLY, DIE SALES AGAINST DIE DETAIL "A" WILL NO LONGER BE AVAILABLE. FUTURE DIE SALES MAY BE ISSUED AGAINST DIE DETAIL "B" OF THE AFFECTED SMD. NOTE: THE NEW DIE SUPPLIED AGAINST DIE DETAIL "B" REQUIRE A SUBSTRATE BIAS TO VSS. THE MIGRATED DEVICE OFFERING WILL BE AVAILABLE WITH THE FOLLOWING OPTIONS: SMD #: 5962-96516 DEVICE TYPE: 01 AVAILABLE RHA DESIGNATORS: R (100Krad (Si)), F (300Krad (Si)), G (500Krad (Si)) DEVICE CLASS: Q, V CASE OUTLINE DESIGNATOR: X (14 LEAD FLAT PACK) OR DIE CODE: 9 LEAD FINISH: A, C, X OR DIE DETAIL: B SHIPMENTS OF THE MIGRATED DEVICE ARE EXPECTED TO BEGIN IN JUNE 2014. See Continuation on page 2.			
20. ADEPT REPRESENTATIVE Timothy L. Meade		21. SIGNATURE 	
		22. DATE 28 February, 2014	

Obsolete SMD PINs

5962	H	96516	01	V 9 A
5962	H	96516	01	Q 9 A
5962	H	96516	01	Q C A
5962	H	96516	01	Q X A
5962	H	96516	01	Q C C
5962	H	96516	01	Q X C
5962	H	96516	01	V C A
5962	H	96516	01	V X A
5962	H	96516	01	V C C
5962	H	96516	01	V X C

Vendor Similar PINs

UT54ACS04-	VDIE
UT54ACS04-	QDIE
UT54ACS04-	PQAH
UT54ACS04-	UQAH
UT54ACS04-	PQCH
UT54ACS04-	UQCH
UT54ACS04-	PVAH
UT54ACS04-	UVAH
UT54ACS04-	PVCH
UT54ACS04-	UVCH

Replace SMD PINs

5962	G	96516	01	Q 9 B
5962	G	96516	01	Q X A
5962	G	96516	01	Q X C
5962	G	96516	01	V 9 B
5962	G	96516	01	V X A
5962	G	96516	01	V X C

Vendor Similar PINs

UT54ACS04-	QDIE
UT54ACS04-	UQAG
UT54ACS04-	UQCG
UT54ACS04-	VDIE
UT54ACS04-	UVAG
UT54ACS04-	UVCG